DECLARATION AND POWER OF ATTORNEY

In re Application of: Jun Li, Chai Hoon Quek, Leong Ming Gan, Hanry Yu, and Kam W. Leong

As a below named inventor, We hereby declare that our residences, post office addresses and citizenships are as stated below next to our names. We believe we are the original or joint inventors of the subject matter which is claimed and for which a patent is sought on the invention entitled: *Microcapsules For Encapsulation Of Bioactive Substances* which was filed in the U.S. Patent and Trademark Office on March 9, 2004, as U.S. Application No.

We hereby state that we have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above. We understand that we have a duty of candor and good faith toward the Patent and Trademark Office, and we acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, §1.56.

We hereby claim foreign priority benefits under Title 35, United States Code, §119 (a)-(d) of the foreign application(s) for patent or inventor's certificate listed below, and have also identified below any foreign application for patent or inventor's certificate disclosing subject matter in common with the above-identified specification and having a filing date before that of the application on which priority is claimed:

Application No.

Country

Filing Date

Priority Claimed Under 35 USC §119

We hereby claim the benefit under Title 35, United States Code, § 119(e) of any United States provisional application(s) listed below:

(Application No.)

(Filing Date)

(Application No.)

(Filing Date)

We hereby claim the benefit under Title 35, United States Code, §120 or 365(c) of any United States application(s) listed below and, insofar as the subject matter disclosed and claimed in the present application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code §112, I acknowledge the duty to disclose material information as defined in Title 37, Code of United States Code §1.56 which became available between the filing date of the prior application and the national or PCT international filing date of this application:

Application No.

Filing Date

Status

We further declare that all statements made herein of our own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statement were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patents issuing thereon.

POWER OF ATTORNEY: The following are hereby appointed to prosecute this application and transact all business in the Patent and Trademark Office connected therewith: Sherry M. Knowles-33,052; W. Scott Petty-35,645; Madeline I. Johnston -36,174; Clark G. Sullivan-36,942; Holmes J. Hawkins-38,913; Steven P. Wigmore-40,447; Charles E. Peeler-45,004; Rebecca J. Kaufman- 44,819; Shane A. Nichols-43,836; Robert Neufeld-48,394; William Isaacs-44,165; Michael S. Pavento-42,985; James M. Hannon-48,565; Natasha Horne Moffitt-53,340; Stephanie D. Adams-47,378; Susanne Hollinger-51,811; Charles Thorpe Jr.-48,782; Michael L. Wach-54,517; Brent R. Bellows-54,709; Monte Rhodes-54,396; James J. Mayberry- P-55,438

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